
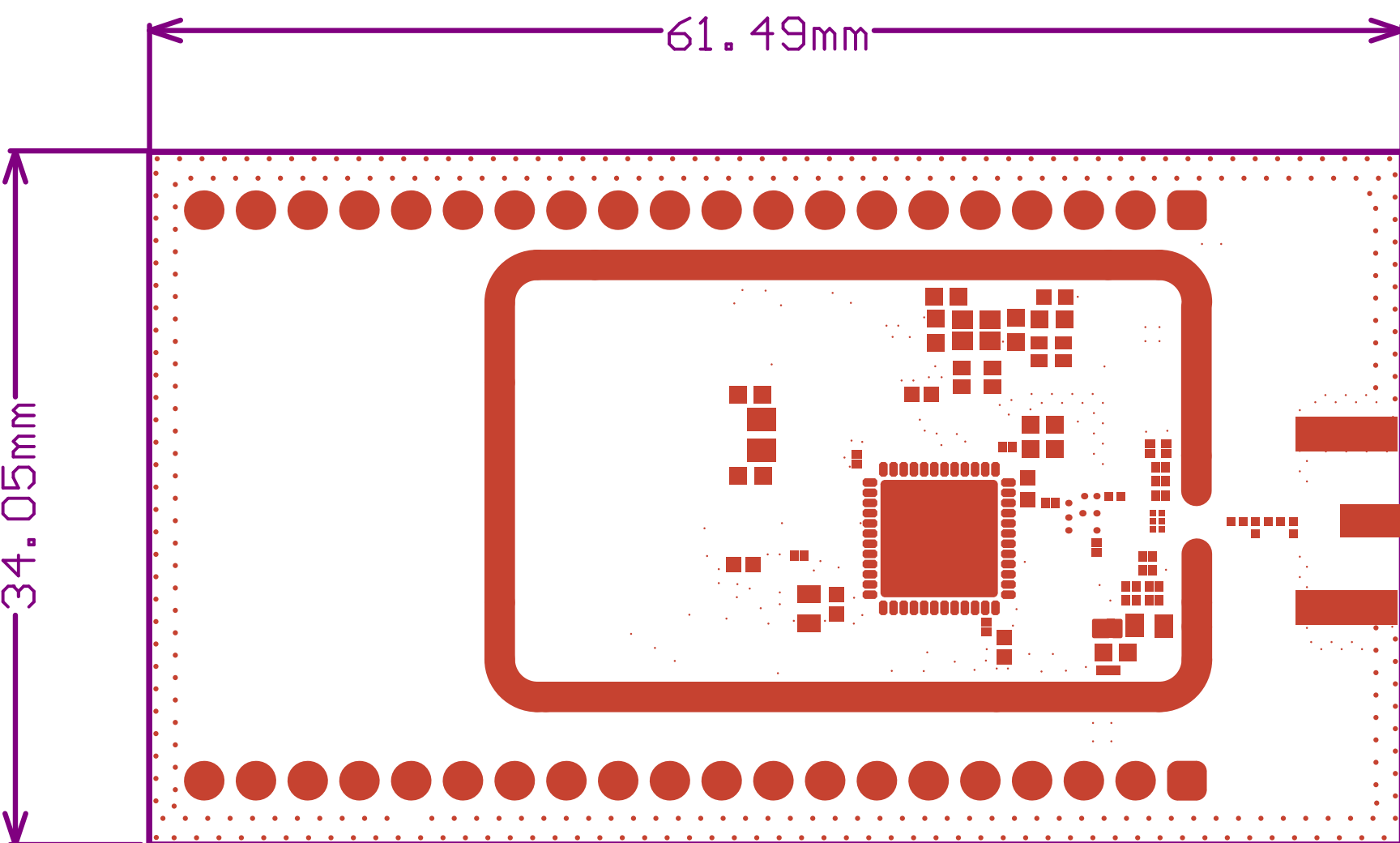

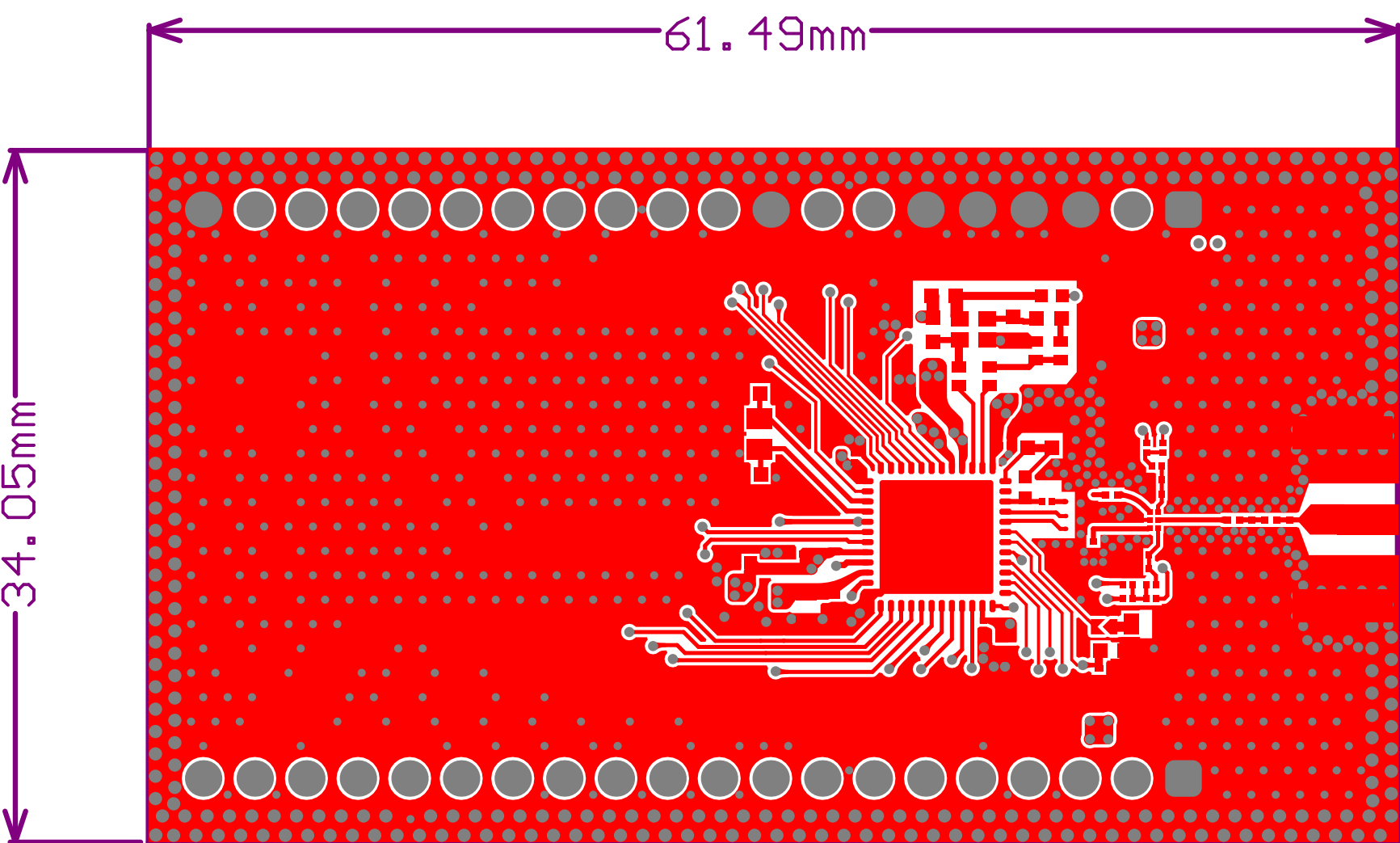



Project: STM32WL_QFN48_IPD_4Layers_IPD_TX_LowPower		
Layer: Top Overlay	Gerber: .GTO	
Variant: [No Variations]	Ref: MB1848_LP	
Date: June 2022	Rev: A	

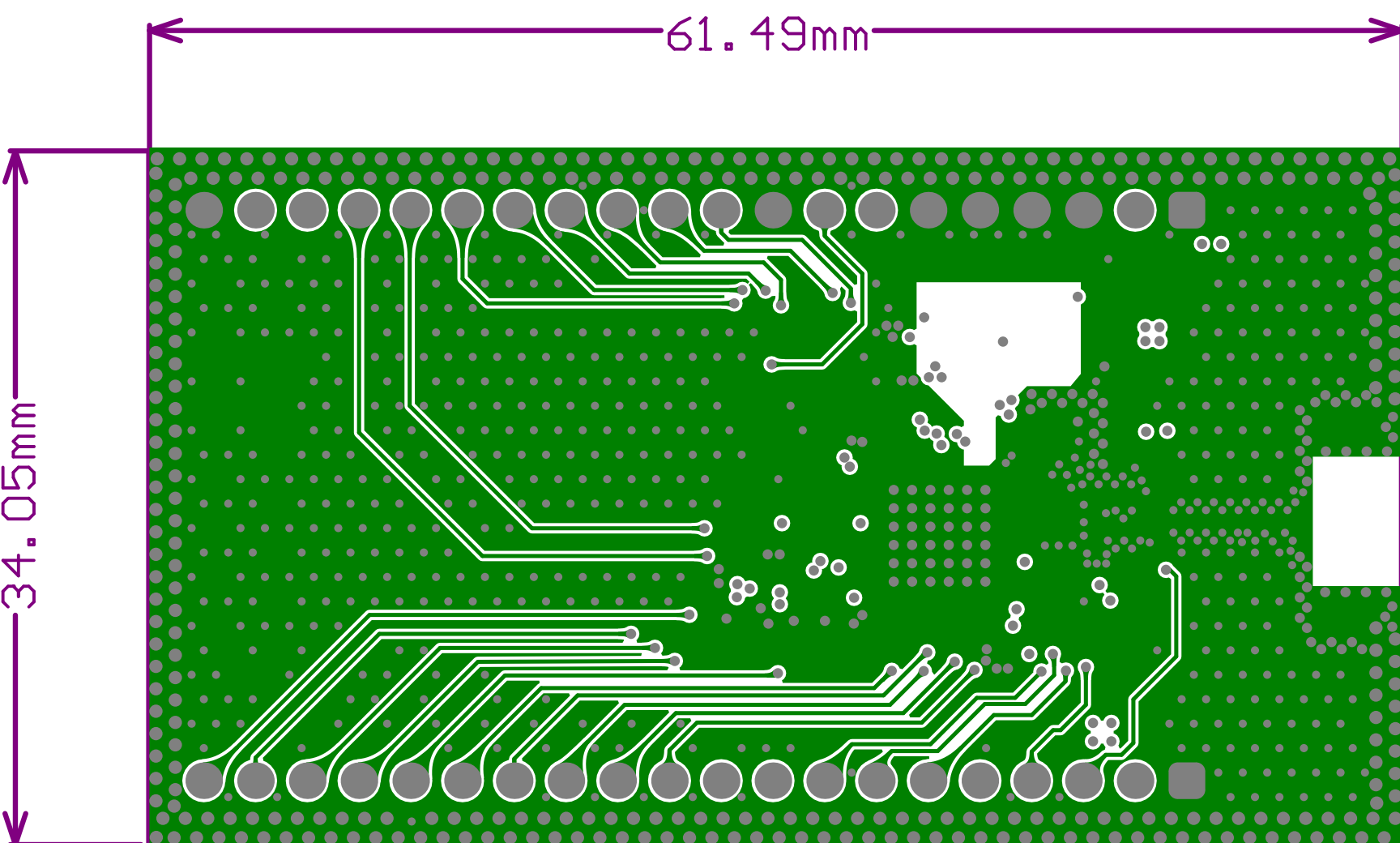



Project: STM32WL_QFN48_IPD_4Layers_IPD_TX_LowPower		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB1848_LP	
Date: June 2022	Rev: A	

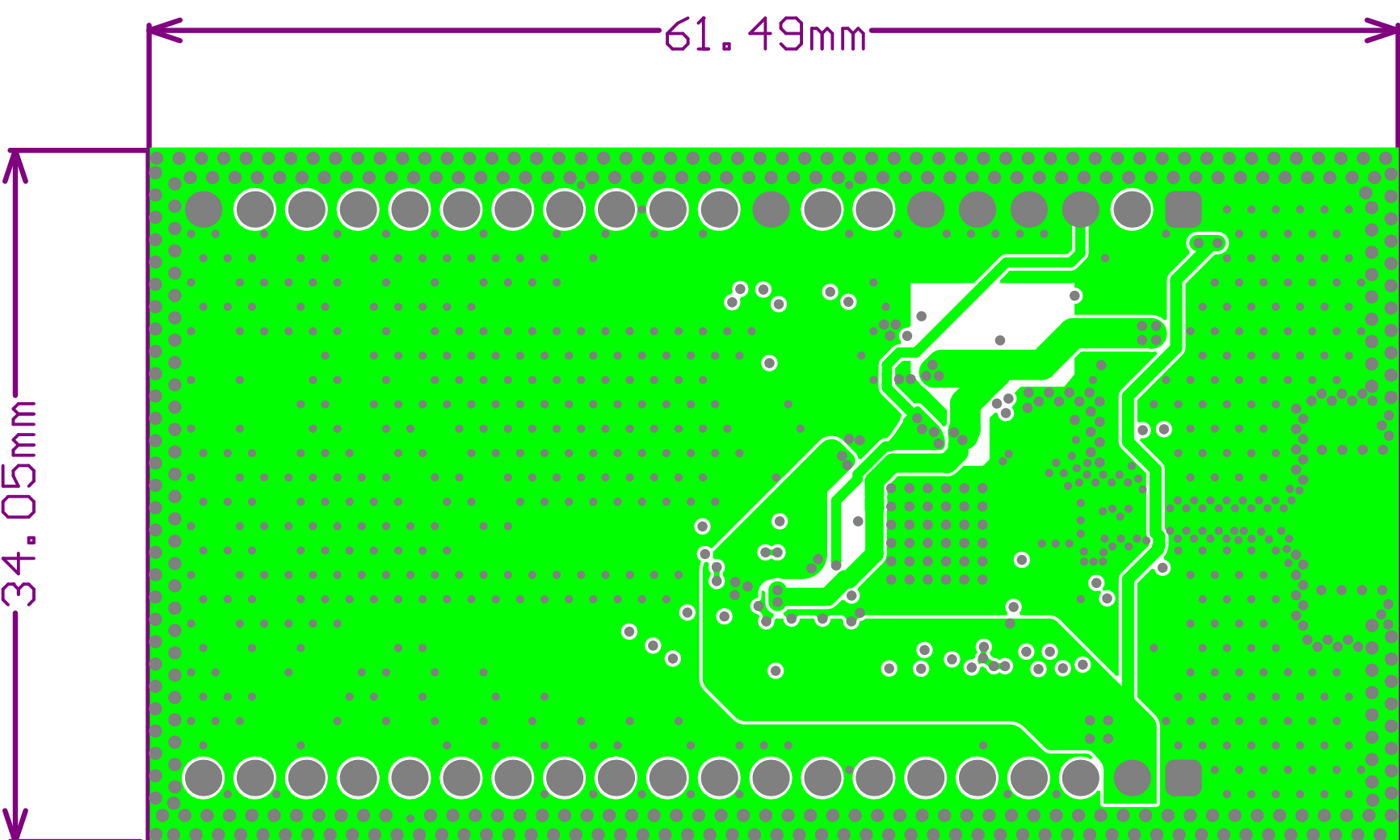



Layer	Name	Material	Thickness	Constant
	Top Overlay			
	Top Solder	Solder Resist	0.39mil	3.5
1	Top Layer		1.38mil	
	Dielectric 2	1 x 2116 + 1 x 106	6.30mil	3.7
2	MidLayer 1		0.69mil	
	Dielectric 1	FR-4	24.02mil	5
3	MidLayer 2		0.69mil	
	Dielectric 3	1 x 2116 + 1 x 106	6.30mil	3.7
4	Bottom Layer		1.38mil	
	Bottom Solder	Solder Resist	0.39mil	3.5
	Bottom Overlay			

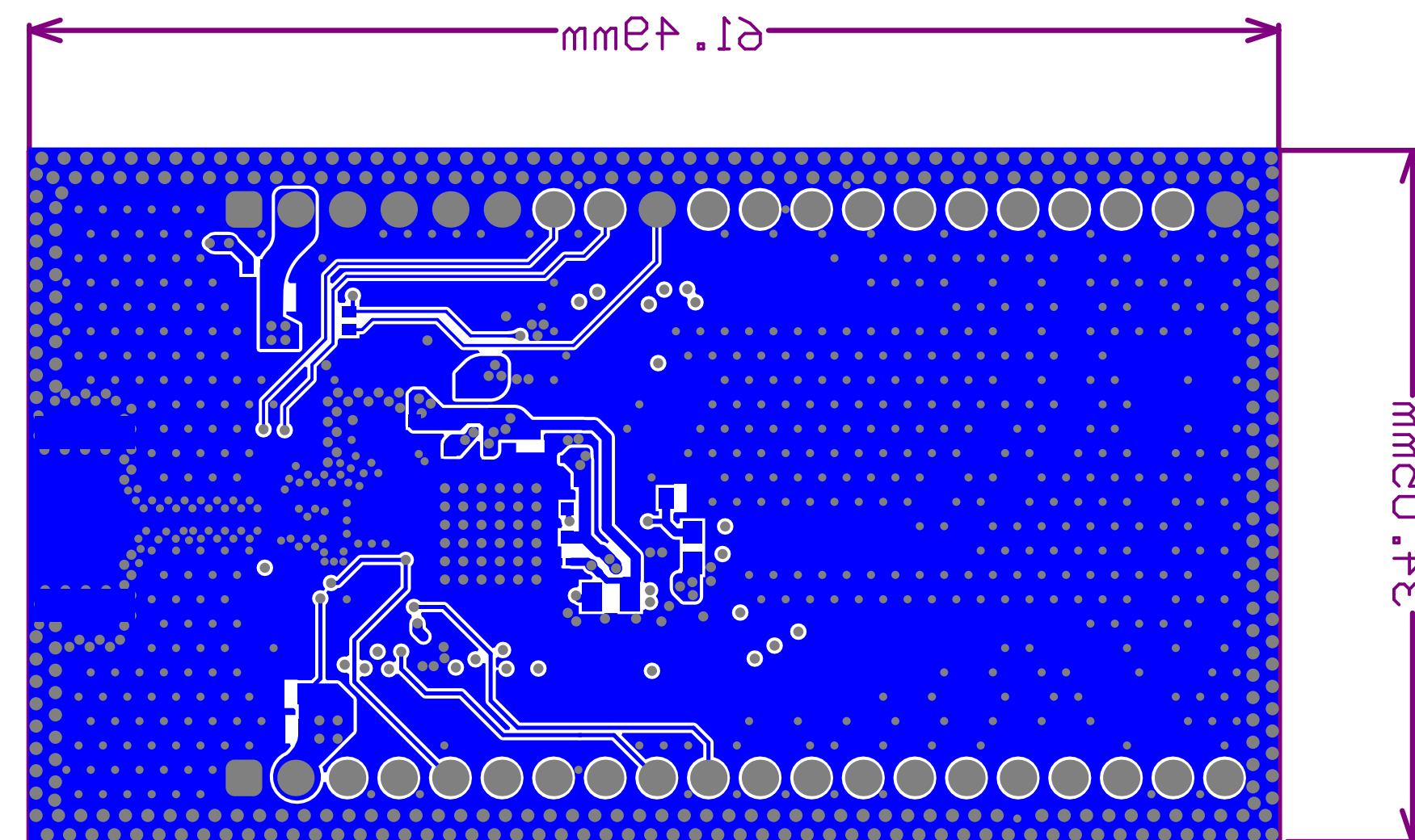
Project: STM32WL_QFN48_IPD_4Layers_IPD_TX_LowPower		
Layer: Top Layer	Gerber: .GTL	
Variant: [No Variations]	Ref: MB1848_LP	
Date: June 2022	Rev: A	




Project: STM32WL_QFN48_IPD_4Layers_IPD_TX_LowPower		
Layer: MidLayer 1	Gerber: .G1	
Variant: [No Variations]	Ref: MB1848_LP	
Date: June 2022	Rev: A	



Project: STM32WL_QFN48_IPD_4Layers_IPD_TX_LowPower		
Layer: MidLayer 2	Gerber: .G2	
Variant: [No Variations]	Ref: MB1848_LP	
Date: June 2022	Rev: A	



Project: STM32WL_QFN48_IPD_4Layers_IPD_TX_LowPower		
Layer: Bottom Layer	Gerber: .GBL	
Variant: [No Variations]	Ref: MB1848_LP	
Date: June 2022	Rev: A	

Gerber File List

Gerber files are used to manufacture the PCB. The files are listed below.

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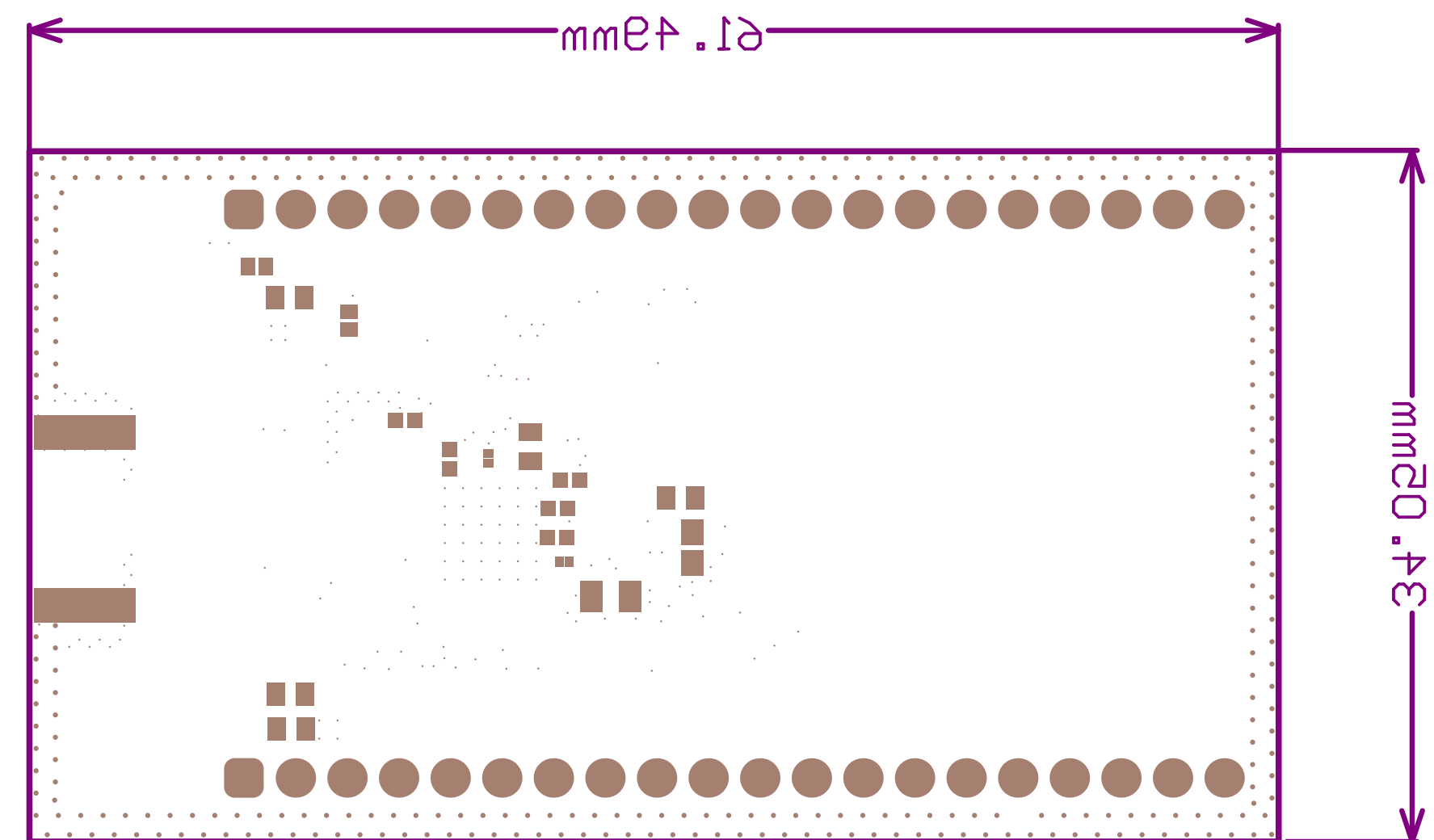
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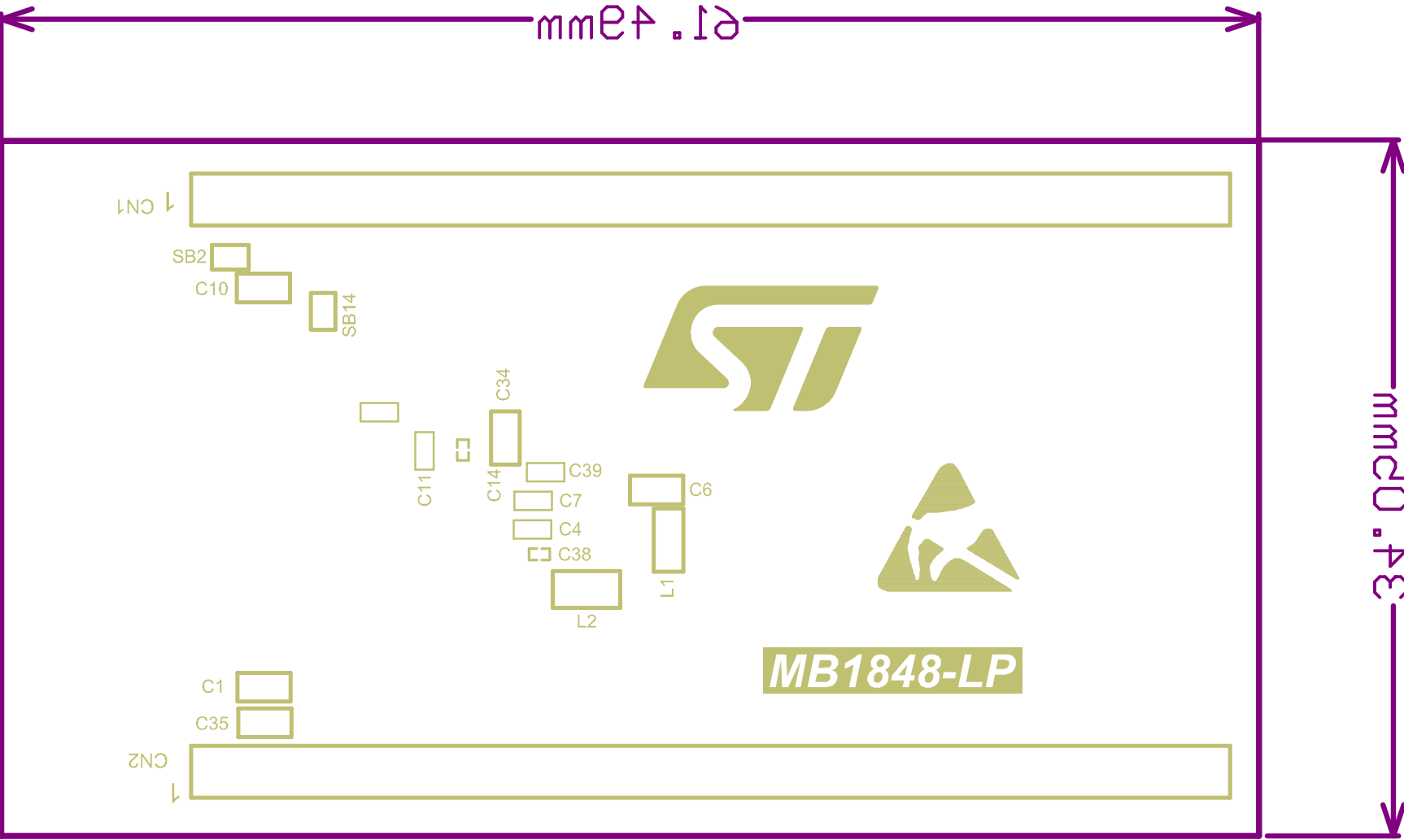
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Project: STM32WL_QFN48_IPD_4Layers_IPD_TX_LowPower		
Layer: Bottom Solder	Gerber:.GBS	
Variant: [No Variations]	Ref: MB1848_LP	
Date: June 2022	Rev: A	



Project: STM32WL_QFN48_IPD_4Layers_IPD_TX_LowPower

Layer: Bottom Overlay

Gerber: GBO

Variant: [No Variations]

Ref: MB1848_LP

Date: June 2022

Rev: A



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template
✧	40	1.000mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)
▽	1060	0.200mm (7.87mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)
	1100 Total							

PCB SPECIFICATIONS :

- A. MATERIAL :

FR-4

☒ TG-170

☐ TG-150

☐ TG-140
- B. MATERIAL FAMILY :

N/A
- C. SOLDERMASK COLOR :

☒ GREEN

☐ BLUE

☐ RED

☐ BLACK
- D. SILKSCREEN COLOR :

☒ WHITE

☐ YELLOW

☐ BLACK
- E. SURFACE FINISH :

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER
- ☐ IMPEDANCE CONTROL :

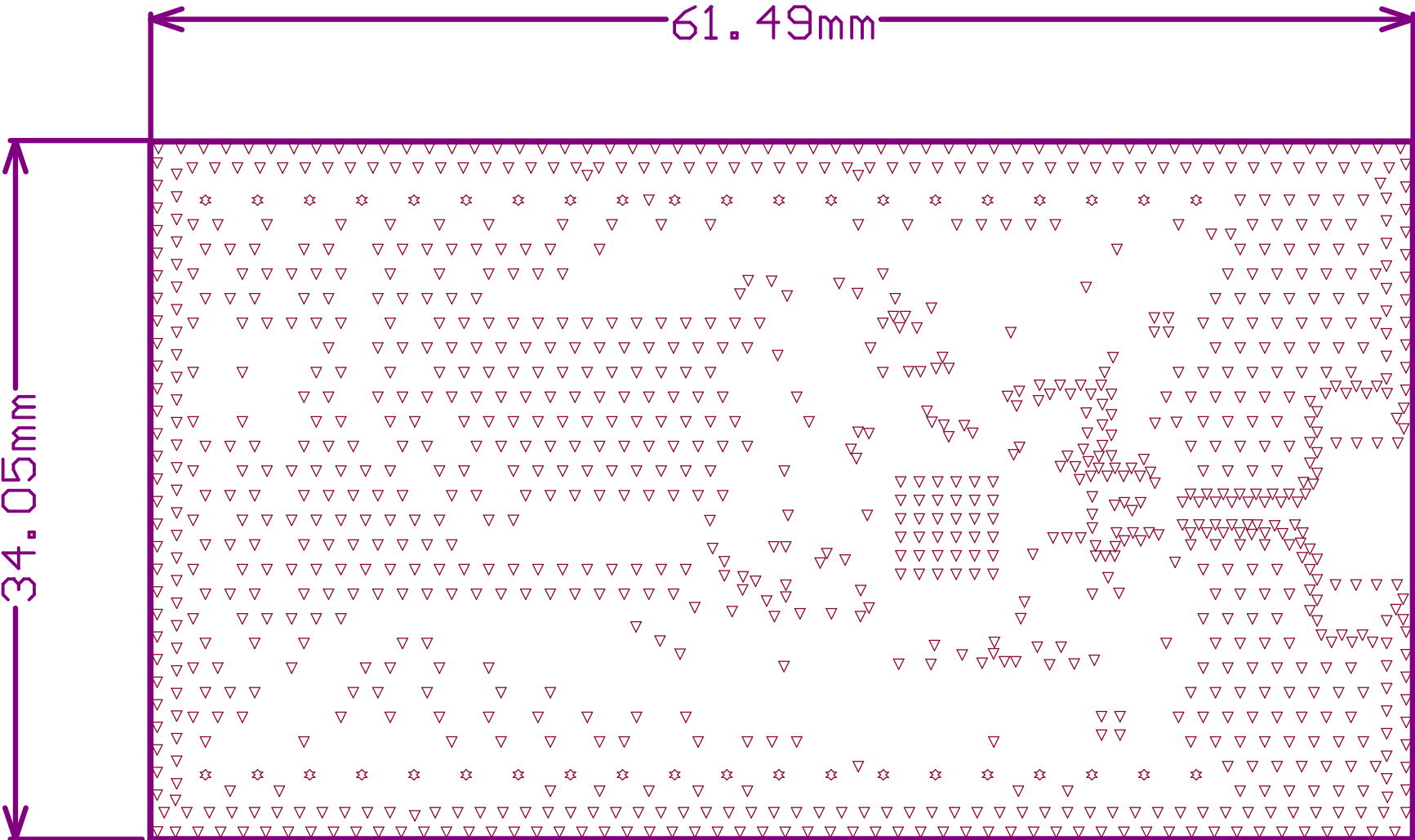
☐ NO


☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)
- G. THROUGH VIA :

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.
- ☐ STACK-UP :

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.



Project: STM32WL_QFN48_IPD_4Layers_IPD_TX_LowPower		
Layer: Drill Drawing	Gerber: .DRL	
Variant: [No Variations]	Ref: MB1848_LP	
Date: June 2022	Rev: A	

IMPEDANCE TABLE					
LAYER	TRACE mils	SPACING mils	IMPEDANCE (Single ended)	IMPEDANCE (Differentiel)	TOL.
TOP	9.84	6.89	50 ohm	NA	+/- 10%